

# XPedite5370

**End of Life**

NXP Dual-Core PowerQUICC™ III MPC8572E Processor-Based Conduction- or Air-Cooled 3U VPX-REDI SBC

Please see [XPedite5970](#)

- ▶ NXP PowerQUICC™ III MPC8572E processor with dual PowerPC e500 cores at up to 1.5 GHz
- ▶ 3U VPX (VITA 46) module
- ▶ Ruggedized Enhanced Design Implementation (REDI)
- ▶ Conduction or air cooling
- ▶ Up to 4 GB (2 GB each) of DDR2-800 ECC SDRAM in two channels
- ▶ Up to 256 MB of NOR flash (with redundancy)
- ▶ Up to 4 GB of NAND flash
- ▶ XMC/PrPMC interface
- ▶ x4 PCI Express or Serial RapidIO P1.A fabric interconnect
- ▶ x4 PCI Express P1.B fabric interconnect
- ▶ Two SerDes Gigabit Ethernet P1 fabric interconnects
- ▶ Two 10/100/1000BASE-T Ethernet ports (optional)
- ▶ Up to two RS-232/422/485 serial P2 ports
- ▶ Front I/O available via plugover module
- ▶ Linux BSP
- ▶ Wind River VxWorks BSP
- ▶ QNX Neutrino BSP
- ▶ Green Hills INTEGRITY BSP



## XPedite5370

The XPedite5370 is a high-performance 3U VPX-REDI single board computer based on the NXP (formerly Freescale) PowerQUICC™ III MPC8572E processor. With dual PowerPC e500 cores running at up to 1.5 GHz, the MPC8572E delivers enhanced performance and efficiency for today's embedded computing applications.

The XPedite5370 supports two separate channels of up to 2 GB each of up to DDR2-800 ECC SDRAM, as well as up to 4 GB of NAND flash and up to 256 MB of NOR flash (with redundancy). The XPedite5370 provides the option of utilizing a PCI Express or Serial RapidIO P1 interconnect, as well as two SerDes Gigabit Ethernet P1 fabric interconnects. The XPedite5370 also supports dual Gigabit Ethernet, GPIO, I<sup>2</sup>C, PMC I/O, XMC I/O, and up to two RS-232/422/485 serial ports through the P2 connector.

The XPedite5370 provides a ruggedized, high-performance, feature-rich solution to support the next generation of rugged embedded applications. Linux, Wind River VxWorks, QNX Neutrino, and Green Hills INTEGRITY Board Support Packages (BSPs) are available.

# X-ES

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### Extreme Engineering Solutions

9901 Silicon Prairie Parkway • Verona, WI 53593  
 Phone: 608.833.1155 • Fax: 608.827.6171  
[sales@xes-inc.com](mailto:sales@xes-inc.com) • <https://www.xes-inc.com>

**Processor**

- NXP (formerly Freescale) PowerQUICC™ III MPC8572E processor
- Dual PowerPC e500 cores at up to 1.5 GHz
- 1 MB of shared L2 cache

**Memory**

- Up to 4 GB (2 GB each) of DDR2-800 ECC SDRAM in two channels
- Up to 256 MB of NOR flash (with redundancy)
- Up to 4 GB of NAND flash

**VPX (VITA 46) P1 I/O**

- x4 PCI Express or Serial RapidIO to P1.A
- x4 PCI Express to P1.B
- Two SerDes Gigabit Ethernet ports (or one 10/100/1000BASE-T port out P1 and one 10/100/1000BASE-T port out P2)
- X12d XMC P16 I/O

**VPX (VITA 46) P2 I/O**

- One 10/100/1000BASE-T port (when two SerDes Gigabit Ethernet P1 ports are not used)
- Up to two RS-232/422/485 serial ports
- I<sup>2</sup>C port
- 3.3 V GPIO signals
- P64s PMC P14 I/O

**XMC/PrPMC Site**

- 32-bit, 66 MHz PCI bus (PMC interface)
- x4 PCIe port (XMC interface)
- P64s P14 I/O support
- X12d P16 I/O support

**Front Panel I/O**

- Front panel RJ-45 Ethernet and micro-DB-9 RS-232 serial ports available via optional plugover module

**Software Support**

- Linux BSP
- Wind River VxWorks BSP
- QNX Neutrino BSP
- Green Hills INTEGRITY BSP

**Physical Characteristics**

- 3U VPX-REDI conduction- or air-cooled form factor
- Dimensions: 100 mm x 160 mm
- 0.8 in. pitch without solder-side cover
- 0.85 and 1.0 in. pitch with solder-side cover

**Environmental Requirements**

- Contact factory for appropriate board configuration based on environmental requirements.
- Supported ruggedization levels (see chart below): 1, 3, 5
  - Conformal coating available as an ordering option

**Power Requirements**

- Maximum power consumption: 29 W (with 1.5 GHz processor), 26 W (with 1.333 GHz processor)

Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient (300 LFM)	-40 to +70°C (600 LFM)	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C (maximum)
Vibration	0.002 g <sup>2</sup> /Hz (maximum), 5 to 2000 Hz	0.04 g <sup>2</sup> /Hz (maximum), 5 to 2000 Hz	0.1 g <sup>2</sup> /Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing

